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*Please check the dimensions of each products in detail.
LAPIS Semiconductor products and ROHM Semiconductor dimensions products have different although they have a same package name.
Part No. Explanation

- When ordering, specify the part number.
- Check each code against the tables shown below.
- Fill in from the left, leaving any extra boxes empty on the right.

**Part No.**

- **B** 4 5 5 8 **F** — **D** **X** **E** 2

**Custom Specification code**

- **Alphabetical symbols specify custom product.**
- **Standard product has no symbols.**

**Packaging and forming specification**

<table>
<thead>
<tr>
<th></th>
<th>E2</th>
<th>Pin 1 fed last</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>(E1)</td>
<td>Pin 1 fed first</td>
</tr>
<tr>
<td>TR</td>
<td>Embossed tape and reel</td>
<td>Pin 1 fed first</td>
</tr>
<tr>
<td>(TL)</td>
<td>Embossed tape and reel</td>
<td>Pin 1 fed last</td>
</tr>
</tbody>
</table>

**Ordering information**

1. A packaging specification is not required for packaging other than taping.
   (Ex.) BA4558F or BA4558F-DX
2. A packaging specification is required for tape packaging.
   (Ex.) Example of E2-oriented embossed taping: BA4558F-E2 or BA4558F-DXE2

**For example**

- **Reel**
  - Leader (first)
  - E2
  - (E1)

- **Reel**
  - Leader (first)
  - TR
  - (TL)

*Take E2 as standard if no special request is made.

Please refer packages from page, A150 for LAPIS Semiconductor products.

---

**Part No. Explanation**

ICs

IC Packages (ROHM)

www.rohm.com
When ordering, specify the part number.

Check each code against the tables shown below.

1. A packaging specification is not required for packaging other than taping.
   (Ex.) BA4558F or BA4558F-DX

2. A packaging specification is required for tape packaging.
   (Ex.) Example of E2-oriented embossed taping: BA4558F-E2 or BA4558F-DX2

### Part No.

<table>
<thead>
<tr>
<th>Part No.</th>
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<tbody>
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<td>54 5</td>
<td>ᄉ</td>
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<tr>
<td>ᄉ</td>
<td>F8</td>
</tr>
</tbody>
</table>

Embossed tape and reel

Pin 1 fed first

**EXD**

Packaging and forming specification

<table>
<thead>
<tr>
<th>Specification</th>
<th>2</th>
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<tbody>
<tr>
<td>E2</td>
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</tr>
<tr>
<td>(E1)</td>
<td></td>
</tr>
<tr>
<td>TR</td>
<td></td>
</tr>
<tr>
<td>(TL)</td>
<td></td>
</tr>
</tbody>
</table>

### Ordering information

Fill in from the left, leaving any extra boxes empty on the right.

#### Embossed tape packaging <Package specification name : E2(E1)>

<table>
<thead>
<tr>
<th>Package ordering unit quantity</th>
<th>Non-Lead Gull Wing Packages</th>
<th>SOP Packages</th>
<th>Power Packages</th>
<th>QFP Packages</th>
<th>BGA/QFN</th>
</tr>
</thead>
<tbody>
<tr>
<td>5,000</td>
<td>SSON004X1216*, SSON004X1010</td>
<td>—</td>
<td>—</td>
<td>—</td>
<td>—</td>
</tr>
<tr>
<td>4,000</td>
<td>WSON008X2120, VS00008X2020, VS00008X2030, VS010X3020, VS010X3030, VM002X1830*</td>
<td>—</td>
<td>—</td>
<td>—</td>
<td>—</td>
</tr>
<tr>
<td>3,000</td>
<td>VSOFS*, HVSOFS/6*, HSON8*, WSOFS/8*, VS0008V2030*, VS0101V3030, VQFN016V3030, WL-CSP (2.8mm and under)</td>
<td>TSSOP-B8, SOP4*, SOP3/6/8*, MSOP6/10*</td>
<td>—</td>
<td>—</td>
<td>—</td>
</tr>
<tr>
<td>2,500</td>
<td>VQFN020V4040, VQFN024V4040, VQFN028V5050, VQFN032V5050, VQFN036V5050, VQFN040V5050, WL-CSP (over 2.81mm)</td>
<td>SOP8/14/16, SSOP-A16, TSSOP-B144, SSOP-8B/14/16/20, SOP-J8/J14, HTSSOP-10/20/28, HTSSOP-J8, TSSOP-B8</td>
<td>—</td>
<td>—</td>
<td>—</td>
</tr>
<tr>
<td>2,000</td>
<td>VQFN040V6060, UQFN044V6060</td>
<td>SOP18/20/24, SSOP-A20/24/32, SSOP-B24/28/40, HTSSOP-B24/30/40, HSOP25</td>
<td>—</td>
<td>HRP5/7*, TO252-3/5, SOT223-4, TO263-7, TO252-J3/J5</td>
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</tr>
<tr>
<td>1,500</td>
<td>VQFN048V7070, UQFN056V7070</td>
<td>SSOP-A44, HTSSOP-A44/A44R/BS4, HSOP28/-M28/-M36</td>
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<td>—</td>
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<tr>
<td>1,000</td>
<td>—</td>
<td>—</td>
<td>—</td>
<td>QFP32, TQFP48V, VQFP48C, HTQFP48V, UQFP64, TQFP64U</td>
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</tr>
<tr>
<td>500</td>
<td>—</td>
<td>—</td>
<td>—</td>
<td>—</td>
<td>TO263-3/5</td>
</tr>
</tbody>
</table>

1) *(Package specification : TR/E1)*  
2) Specification differ by package size of WL-CSP  
3) WL-CSP Package Specification : E2 (standard)

#### Tray packaging

<table>
<thead>
<tr>
<th>Pin pitch: 0.8 mm</th>
<th>Pin pitch: 0.65 mm</th>
<th>Pin pitch: 0.5 mm</th>
<th>Pin pitch: 0.4 mm</th>
<th>Dimensions d×e(mm)</th>
<th>Individual package quantity</th>
<th>Package ordering unit quantity</th>
<th>Tension End dimensions AxB/C (mm)</th>
</tr>
</thead>
<tbody>
<tr>
<td>QFP32</td>
<td>—</td>
<td>VQFP48C</td>
<td>—</td>
<td>175×166</td>
<td>100</td>
<td>1,000</td>
<td>60×200×200</td>
</tr>
<tr>
<td>QFP44</td>
<td>SQFP-752/64</td>
<td>VQFP64/80, TQFP48V/64</td>
<td>UQFP80</td>
<td>216×116</td>
<td>50</td>
<td>1,000</td>
<td>70×130×510</td>
</tr>
<tr>
<td>QFP-A64, QFP80/780</td>
<td>—</td>
<td>VQFP100, TQFP100V, HTQFP100V</td>
<td>TQFP128U</td>
<td>256×166</td>
<td>50</td>
<td>500</td>
<td>75×200×290</td>
</tr>
<tr>
<td>QFP120</td>
<td>—</td>
<td>—</td>
<td>—</td>
<td>322.6×135.9</td>
<td>24</td>
<td>240</td>
<td>75×140×338</td>
</tr>
</tbody>
</table>
Please refer packages from page, A150 for LAPIS Semiconductor products.
QFP Packages

<table>
<thead>
<tr>
<th>VQFP48C</th>
<th>VQFP64</th>
<th>VQFP80</th>
<th>VQFP100</th>
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</thead>
<tbody>
<tr>
<td><img src="VQFP48C.png" alt="VQFP48C diagram" /></td>
<td><img src="VQFP64.png" alt="VQFP64 diagram" /></td>
<td><img src="VQFP80.png" alt="VQFP80 diagram" /></td>
<td><img src="VQFP100.png" alt="VQFP100 diagram" /></td>
</tr>
<tr>
<td>Tray: 1,000pcs</td>
<td>Tray: 1,000pcs</td>
<td>Tray: 1,000pcs</td>
<td>Tray: 500pcs</td>
</tr>
<tr>
<td>Embossed carrier tape: 1,500pcs</td>
<td>Embossed carrier tape: 1,000pcs</td>
<td>Embossed carrier tape: 1,000pcs</td>
<td>Embossed carrier tape: 500pcs</td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>UQFP80</th>
<th>TQFP128U</th>
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</thead>
<tbody>
<tr>
<td><img src="UQFP80.png" alt="UQFP80 diagram" /></td>
<td><img src="TQFP128U.png" alt="TQFP128U diagram" /></td>
</tr>
<tr>
<td>Tray: 1,000pcs</td>
<td>Tray: 500pcs</td>
</tr>
<tr>
<td>Embossed carrier tape: 1,000pcs</td>
<td></td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>HTQFPV48V</th>
<th>HTQFP100V</th>
</tr>
</thead>
<tbody>
<tr>
<td><img src="HTQFPV48V.png" alt="HTQFPV48V diagram" /></td>
<td><img src="HTQFP100V.png" alt="HTQFP100V diagram" /></td>
</tr>
<tr>
<td>Tray: 1,000pcs</td>
<td>Tray: 500pcs</td>
</tr>
<tr>
<td>Embossed carrier tape: 1,500pcs</td>
<td></td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>VMMP008Z1830</th>
</tr>
</thead>
<tbody>
<tr>
<td><img src="VMMP008Z1830.png" alt="VMMP008Z1830 diagram" /></td>
</tr>
<tr>
<td>Embossed carrier tape: 4,000pcs</td>
</tr>
</tbody>
</table>
SON Packages

SSON-X<Pin Pitch:0.65mm>

- SS0N004X1010
- SS0N004X1216

VSON-V<Pin Pitch:0.5mm>

- VSON008V2030
- VSON010V3030

VSON-X<Pin Pitch:0.5mm>

- VSON008X2020
- VSON010X3020
- VSON010X3030

Please refer packages from page, A150 for LAPIS Semiconductor products.
**QFN Packages**

**QFN028 (Pin Pitch: 0.4mm)**

- **QFN028 (Powerervation series)**
  - Tape: 250, 500, 1,000, 5,000 pcs

**QFN032 (Pin Pitch: 0.5mm)**

- **QFN032 (Powerervation series)**
  - Tape: 250, 500, 1,000, 5,000 pcs

**VQFN-V (Pin Pitch: 0.5mm)**

- **VQFN016V3030**
  - Embossed carrier tape: 3,000 pcs
- **VQFN020V4040**
  - Embossed carrier tape: 2,500 pcs
- **VQFN024V4040**
  - Embossed carrier tape: 2,500 pcs
- **VQFN028V5050**
  - Embossed carrier tape: 2,500 pcs
- **VQFN032V5050**
  - Embossed carrier tape: 2,500 pcs
- **VQFN040V6060**
  - Embossed carrier tape: 2,000 pcs
- **VQFN048V7070**
  - Embossed carrier tape: 1,500 pcs

Please refer packages from page, A150 for LAPIS Semiconductor products.
Please refer packages from page A150 for LAPIS Semiconductor products.

**QFN Packages**

**UQFN-V<Pin Pitch:0.4mm>**

<table>
<thead>
<tr>
<th>Model</th>
<th>Dimensions (mm)</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>UQFN036V5050</td>
<td>5.0 x 0.1</td>
<td>Embossed carrier tape 2,500pcs</td>
</tr>
<tr>
<td>UQFN040V5050</td>
<td>5.0 x 0.1</td>
<td>Embossed carrier tape 2,500pcs</td>
</tr>
<tr>
<td>UQFN044V6060</td>
<td>6.0 x 0.1</td>
<td>Embossed carrier tape 2,000pcs</td>
</tr>
<tr>
<td>UQFN056V7070</td>
<td>7.0 x 0.1</td>
<td>Embossed carrier tape 1,500pcs</td>
</tr>
</tbody>
</table>

**SOP Packages**

**SOP<Pin Pitch:1.27mm>**

<table>
<thead>
<tr>
<th>Model</th>
<th>Dimensions (mm)</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>SOP8</td>
<td>5.0 ± 0.2</td>
<td>Embossed carrier tape 2,500pcs</td>
</tr>
<tr>
<td>SOP14</td>
<td>8.7 ± 0.2</td>
<td>Embossed carrier tape 2,500pcs</td>
</tr>
<tr>
<td>SOP16</td>
<td>10±2.2</td>
<td>Embossed carrier tape 2,500pcs</td>
</tr>
<tr>
<td>SOP18</td>
<td>11.2 ± 0.2</td>
<td>Embossed carrier tape 2,000pcs</td>
</tr>
<tr>
<td>SOP20</td>
<td>12.5 ± 0.2</td>
<td>Embossed carrier tape 2,000pcs</td>
</tr>
<tr>
<td>SOP24</td>
<td>16.0 ± 0.2</td>
<td>Embossed carrier tape 2,000pcs</td>
</tr>
</tbody>
</table>

**ICs**

**IC Packages (ROHM)**

Please visit www.rohm.com for more information.
Please refer packages from page, A150 for LAPIS Semiconductor products.

### SOP Packages

#### SSOP-A<Pin Pitch:0.8mm>

- **SSOP-A16**
- **SSOP-A20**
- **SSOP-A24**

#### SSOP-B<Pin Pitch:0.65mm>

- **SSOP-B8**
- **SSOP-B14**
- **SSOP-B16**
- **SSOP-B20**
- **SSOP-B24**
- **SSOP-B28**
- **SSOP-B40**

(Unit: mm)
Please refer packages from page A150 for LAPIS Semiconductor products.

**SOP Packages**

**JEDEC<Pin Pitch:1.27mm/0.65mm>**

- **SOP-J8**
- **SOP-J14**
- **TSSOP-B8**
- **TSSOP-B14J**

**HSOP Packages**

**HSOP<Pin Pitch:0.8mm>**

- **HSOP25**
- **HSOP-M28**
- **HSOP-M36**
Please refer packages from page A150 for LAPIs Semiconductor products.

**HSOP Packages**

- **HTSOP-J**<br>Pin Pitch: 1.27mm<br>
  - Embossed carrier tape: 2,500pcs

- **HTSSOP-A**<br>Pin Pitch: 0.8mm<br>
  - Embossed carrier tape: 1,500pcs

- **HTSSOP-B**<br>Pin Pitch: 0.65mm<br>
  - Embossed carrier tape: 2,500pcs

- **HTSSOP-B16**
  - Embossed carrier tape: 2,500pcs

- **HTSSOP-B20**
  - Embossed carrier tape: 2,500pcs

- **HTSSOP-B28**
  - Embossed carrier tape: 2,500pcs

- **HTSSOP-B30**
  - Embossed carrier tape: 2,000pcs

- **HTSSOP-B40**
  - Embossed carrier tape: 2,000pcs

- **HTSSOP-B54**
  - Embossed carrier tape: 1,500pcs
**Small Packages**

**SOP type**

**SOP4**

**SSOP3**

**SSOP5**

**SSOP6**

**MSOP8**

**MSOP10**

**Non-Lead Packages**

**Non-Lead**

**VSOF5**

**HVSOF5**

**HVSOF6**

**HSON8**

Please refer packages from page, A150 for LAPIS Semiconductor products.
Non-Lead Packages

Optical Non-Lead

WSOF5(Clear type)

WSOF6(Clear type)

WSO08X2120(Clear type)

Power Packages

POWER-3PIN

TO220CP-3

TO252-3

TO252-J3

TO263-3

POWER-4PIN

SOT223-4

Please refer packages from page, A150 for LAPIS Semiconductor products.
Please refer packages from page, A150 for LAPIS Semiconductor products.

Power Packages

POWER-5PIN

TO220FP-5

TO252-5

HRP5

Container tube/500pcs

Embosed carrier tape/2,000pcs

Embosed carrier tape/2,000pcs

TO263-5

TO252-J5

Embosed carrier tape/500pcs

Embosed carrier tape/2,000pcs

POWER-7PIN

HRP7

TO263-7

Embosed carrier tape/2,000pcs

Embosed carrier tape/2,000pcs
Please refer packages from page, A150 for LAPIS Semiconductor products.

**BGA Packages**

**VBGA-W<Pin Pitch:0.5mm>**

- **VBGA048W040**
- **VBGA099W060**

**WL-CSP Packages**

**VCSP<Pin Pitch:0.5mm>**

<table>
<thead>
<tr>
<th>VCSP85H</th>
<th>VCSP50L</th>
<th>VCSP35L</th>
<th>VCSP30L</th>
</tr>
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<tbody>
<tr>
<td><img src="#" alt="Diagram" /></td>
<td><img src="#" alt="Diagram" /></td>
<td><img src="#" alt="Diagram" /></td>
<td><img src="#" alt="Diagram" /></td>
</tr>
</tbody>
</table>
| 2.8mm² and under: 3,000pcs  
Over 2.81mm²: 2,500pcs | 2.8mm² and under: 3,000pcs  
Over 2.81mm²: 2,500pcs | 2.8mm² and under: 3,000pcs  
Over 2.81mm²: 2,500pcs  
Embosed carrier tape:3,000pcs | 2.8mm² and under: 3,000pcs  
Over 2.81mm²: 2,500pcs  
Embosed carrier tape:3,000pcs |

**UCSP<Pin Pitch:0.4mm>**

<table>
<thead>
<tr>
<th>UCSP75M</th>
<th>UCSP50L</th>
<th>UCSP35L</th>
<th>UCSP30L</th>
<th>UCSP25L</th>
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</thead>
<tbody>
<tr>
<td><img src="#" alt="Diagram" /></td>
<td><img src="#" alt="Diagram" /></td>
<td><img src="#" alt="Diagram" /></td>
<td><img src="#" alt="Diagram" /></td>
<td><img src="#" alt="Diagram" /></td>
</tr>
</tbody>
</table>
| 2.8mm² and under: 3,000pcs  
Over 2.81mm²: 2,500pcs | 2.8mm² and under: 3,000pcs  
Over 2.81mm²: 2,500pcs | 2.8mm² and under: 3,000pcs  
Over 2.81mm²: 2,500pcs  
Embosed carrier tape:3,000pcs | 2.8mm² and under: 3,000pcs  
Over 2.81mm²: 2,500pcs  
Embosed carrier tape:3,000pcs | Embosed carrier tape:3,000pcs |

**XCSP<Pin Pitch:0.35mm>**

- **XCSP30L**

   Embossed carrier tape:3,000pcs
LAPIS Semiconductor LSI Package List

<table>
<thead>
<tr>
<th>No.</th>
<th>PKG type</th>
<th>PKG Symbol</th>
<th>Title</th>
<th>TRAY</th>
<th>T&amp;R</th>
<th>TUBE</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>SOP</td>
<td>MA SOP8-200-1.27</td>
<td>—</td>
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<td>—</td>
<td>—</td>
</tr>
<tr>
<td>2</td>
<td>SSOP</td>
<td>MB SSOP16-0225-0.65</td>
<td>4,760</td>
<td>2,500</td>
<td>—</td>
<td>—</td>
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<tr>
<td>3</td>
<td>SSOP</td>
<td>MB SSOP30-56-0.65</td>
<td>2,000</td>
<td>2,000</td>
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<td>—</td>
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<tr>
<td>4</td>
<td>SSOP</td>
<td>MB SSOP32-430-1.00</td>
<td>1,280</td>
<td>1,000</td>
<td>—</td>
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</tr>
<tr>
<td>5</td>
<td>SSOP</td>
<td>MB SSOP60-700-0.65</td>
<td>600</td>
<td>600</td>
<td>—</td>
<td>—</td>
</tr>
<tr>
<td>6</td>
<td>SSOP</td>
<td>MB SSOP64-525-0.80</td>
<td>—</td>
<td>800</td>
<td>—</td>
<td>—</td>
</tr>
<tr>
<td>7</td>
<td>TSOP</td>
<td>TD TSSOP20-0225-0.65</td>
<td>4,160</td>
<td>2,000</td>
<td>—</td>
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<tr>
<td>8</td>
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<td>TA TSOP80-08134-0.55</td>
<td>1,950</td>
<td>—</td>
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<td>—</td>
</tr>
<tr>
<td>9</td>
<td>TSOP</td>
<td>TA TSOP120-08134-0.50</td>
<td>1,170</td>
<td>1,000</td>
<td>—</td>
<td>—</td>
</tr>
<tr>
<td>10</td>
<td>TSOP</td>
<td>TA TSOP120-08134-0.65</td>
<td>1,080</td>
<td>1,000</td>
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<td>—</td>
</tr>
<tr>
<td>11</td>
<td>QFP</td>
<td>GA QFP44-910-0.80</td>
<td>1,440</td>
<td>1,000</td>
<td>—</td>
<td>—</td>
</tr>
<tr>
<td>12</td>
<td>QFP</td>
<td>GA QFP56-910-0.65</td>
<td>1,440</td>
<td>1,000</td>
<td>—</td>
<td>—</td>
</tr>
<tr>
<td>13</td>
<td>QFP</td>
<td>GA QFP64-1414-0.50</td>
<td>840</td>
<td>—</td>
<td>—</td>
<td>—</td>
</tr>
<tr>
<td>14</td>
<td>QFP</td>
<td>GA QFP64-1420-0.80</td>
<td>600</td>
<td>—</td>
<td>—</td>
<td>—</td>
</tr>
<tr>
<td>15</td>
<td>QFP</td>
<td>GA QFP80-1414-0.65</td>
<td>840</td>
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<td>—</td>
</tr>
<tr>
<td>16</td>
<td>QFP</td>
<td>GA QFP100-1420-0.65</td>
<td>600</td>
<td>—</td>
<td>—</td>
<td>—</td>
</tr>
<tr>
<td>17</td>
<td>QFP</td>
<td>GA QFP100-1414-0.50</td>
<td>750</td>
<td>—</td>
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</tr>
<tr>
<td>18</td>
<td>QFP</td>
<td>GA QFP128-1420-0.50</td>
<td>420</td>
<td>—</td>
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<tr>
<td>19</td>
<td>QFP</td>
<td>GA QFP128-2828-0.80</td>
<td>240</td>
<td>—</td>
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<tr>
<td>20</td>
<td>QFP</td>
<td>GA LQFP32-0707-0.80</td>
<td>2,500</td>
<td>1,000</td>
<td>—</td>
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</tr>
<tr>
<td>21</td>
<td>QFP</td>
<td>GA LQFP144-2020-0.50</td>
<td>600</td>
<td>—</td>
<td>—</td>
<td>—</td>
</tr>
</tbody>
</table>

LAPIS Semiconductor LSI Part No. Explanation

Product names are assigned to our semiconductor devices using the following convention, starting with the character "M".

```
M 00000000000 0 000 Z
```

**Device Function**
The device functions are classified as follows:

- MD: DRAM
- MR: P2ROM™, OTPROM
- MS: Video Memory
- ML: Logic
- MK: Module, chip set
- MT: Driver

**Device Code**
The device code expresses a function specific to a device using a combination of numbers and alphanumeric characters.

**Character Symbol**
The character symbol is added to indicate the modification of an existing product, to emphasize a specification that differs from the standard specification of an existing product, or to indicate a design standard.

**Package Symbol**
The package symbol expresses the type and lead bending profile of a package in two digits.

**Option Classification Symbol**
The option classification symbol is used to distinguish between the option code and the package symbol.

**Derived Code**
The derived code indicates the speed ranking for DRAM products and is used as a derived code for logic products.

**Option Code**
The option code indicates a symbol that identifies the specification of a product with an option.

The following shows the convention of item name assignment for conventional products.

- The actual package profile is not shown here.

```
MSM 66507 JS
```

**Process Classification**
A: Analog
C: Bi-CMOS, multi-chip product

**Circuit Category**
L: Bipolar logic
M: MOS

**Package Profile**
- Analog
- Bipolar logic
- MOS
These package size are an example. For details, please inquire to the sales.

**SOP Packages**

### SOP

**SOP8-200-1.27**

![SOP8-200-1.27 Diagram](image)

**SSOP**

#### (P-)SSOP16-0225-0.65

![P-SSOP16-0225-0.65 Diagram](image)

#### (P-)SSOP30-56-0.65

![P-SSOP30-56-0.65 Diagram](image)

#### SSOP32-430-1.00

![SSOP32-430-1.00 Diagram](image)

#### SSOP60-700-0.65

![SSOP60-700-0.65 Diagram](image)

#### SSOP64-525-0.80

![SSOP64-525-0.80 Diagram](image)

#### (P-)TSSOP20-0225-0.65

![P-TSSOP20-0225-0.65 Diagram](image)

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A151
These package size are an example. For details, please inquire to the sales.

**SOP Packages**

**TSOP (Type I)**

**TSOP (Type II)**

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**IC Packages**

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A152  www.rohm.com
These package size are an example. For details, please inquire to the sales.
These package sizes are an example. For details, please inquire to the sales.
DIP Packages

DIP8

QFN Packages

VQFN

WQFN

These package sizes are examples. For details, please inquire to the sales.
QFN Packages

WQFN

(P)WQFN28-0404-0.40
(P)WQFN28-0404-0.50
(P)WQFN32-0505-0.50

(P)WQFN40-0505-0.40
(P)WQFN40-0606-0.50
(P)WQFN64-0909-0.50

C-QFN

C-QFN24-8585-1.00

WSON Packages

WSON

P-WSON10-0303-0.50

These package size are an example. For details, please inquire to the sales.
BGA Packages

**TFBGA**

S-VFBGA25-2.76 × 2.50-0.5

TFBGA96-9.0 × 13.0-0.80

P-TFBGA144-1111-0.80

**WL-CSP Packages**

**WCSP**

S-UFLGA20-1.84 × 2.14-0.40 (WCSP20)

S-UFLGA34-2.59 × 2.96-0.40-W (WCSP34)

S-UFLGA48-3.06 × 2.96-0.40-W (WCSP48)

S-VFLGA67-4.69 × 3.12-0.40-W (WCSP67)

These package size are an example. For details, please inquire to the sales.

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